

MAY 22 2002

IN RE APPLICATION OF: Masato HARUKA, et al.

GAU: 2859

EXAMINER:

FOR: THERMOELECTRIC MODULE AND METHOD OF ASSEMBLING THE THERMOELECTRIC MODULE IN RADIATING MEMBER

INFORMATION DISCLOSURE/RELATED CASE STATEMENT UNDER 37 CFR 4.97

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MODULE IN
DER 376FR

Applicant(s) wish to disclose the following information.

☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.

☐ A check is attached in the amount required under 37 CFR §1.17(p).

☒ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.

☐ A check is attached in the amount required under 37 CFR §1.17(p).

- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

■ Please charge any additional fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

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DOCKET NO: 220130US2X

SERIAL NO: 10/083,598

Sheet 1 of 1

Group Art Unit: 2859



STATEMENT OF RELEVANCY

Reference AV on Form 1449:

This reference discloses a thermoelectric module for thermoelectric cooling in which upper and lower substrates are the same in size in Fig. 3.13.

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Form PTO 1449
(Modified)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY DOCKET NO.
220130US2XSERIAL NO.
10/083,598

LIST OF REFERENCES CITED BY APPLICANT

APPLICANT

Masato ITAKURA, et al.

FILING DATE
February 27, 2002GROUP
2859

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES	NO
	AO					
	AP					
	AQ					
	AR					
	AS					
	AT					
	AU					

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

	AV	K. I. UEMURA, et al., pages 52-55, "THERMOELECTRIC SEMICONDUCTOR AND ITS APPLICATION" Published by Nikkan Kogyo Shinbunsha, 1998
	AW	
	AX	
	AY	
	AZ	

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Examiner

Date Considered

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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LIST OF RELATED CASES

<u>Docket Number</u>	<u>Serial or Patent No.</u>	<u>Filing or Issue Date</u>	<u>Status or Patentee</u>
213731US2	09/964,371	09/28/01	PENDING
218198US2	10/059,392	01/31/02	PENDING
220130US2X*	10/083,598	02/27/02	PENDING

*Present application; listed for information
GJM/ae

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